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To the Honorable Commissioner of Patents and Trademarks, U.S. Patent and Trademark Office, Washington, D.C. 20503
103062634 original documents or copy thereof.

1. Name of conveying parties

Shoei KOBAYASHI, Tamotsu YAMAGAMI, Shin-Ichi
KADOWAKI, Takashi ISHIDA, Cornelis Marinus SCHEP, Hermanus
Johannes BORGAdditional name(s) of conveying party(ies)
attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment
☐ Security Agreement
☐ Merger
☐ Change of Name
☐ OtherExecution Date(s): January 24, January 25, January 27, January 27,
February 11 and February 14, 2005

2. Name and address of receiving party(ies)

SONY CORPORATION
7-35 Kitashinagawa 6-chome,
Shinagawa-Ku, Tokyo 141-0001, Japan

And

MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD.
1006, Oaza Kadoma, Kadoma-shi,
Osaka 571-8501 Japan

And

KONINKLIJKE PHILIPS ELECTRONICS N.V.
Groenewoudseweg 1,
5621 BA Eindhoven NetherlandsAdditional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: _____

A. Patent Application No. 10/515,191.

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: WILLIAM S. FROMMER
Internal Address: FROMMER LAWRENCE & HAUG LLP
Street Address: 745 FIFTH AVENUE
City: NEW YORK State: NY Zip: 10151

6. Total number of applications and patents involved

1

7. Total fee (37 CFR 3.41)

\$ 40.00☒ Enclosed☐ Authorized to be charged to deposit account 50-0320

8. Deposit account number:

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Thomas F. Presson

Name of Person Signing

Signature

August 9, 2005

Date

08/12/2005 DBYRNE 00000032 10515191

01-FC-0021

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00301975

PATENT
REEL: 016870 FRAME: 0881

ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

DISC-SHAPED RECORDING MEDIUM, DISC DRIVING DEVICE AND DISC PRODUCING METHOD

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, 1) SONY CORPORATION, a Japanese corporation, with offices at 7-35, Kitashinagawa 6-chome, Shinagawa-ku, Tokyo 141-0001 Japan, 2) MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD., a Japanese corporation, with offices at 1006, Oaza Kadoma, Kadoma-shi, Osaka 571-8501 Japan and 3) KONINKLIJKE PHILIPS ELECTRONICS N.V., a Dutch corporation, with offices at Groenewoudseweg 1, 5621 BA Eindhoven Netherlands (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: International Serial Number: PCT/JP03/06423, International Filing Date: 22 May 2003.

This assignment executed on the dates indicated below.

Shoei KOBAYASHI

Name of first or sole inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of first or sole inventor

Shoei Kobayashi

24 January 2005

Signature of first or sole inventor

Date of this assignment

Tamotsu YAMAGAMI

Name of second inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of second inventor

Tamotsu Yamagami

January 25, 2005

Signature of second inventor

Date of this assignment

PATENT of 2

REEL: 016870 FRAME: 0882

Shin-ichi KADOWAKI

Name of third inventor

Execution date of U.S. Patent Application

Hyogo, Japan

Residence of third inventor

Signature of third inventor

Date of this assignment

Takashi ISHIDA

Name of fourth inventor

Execution date of U.S. Patent Application

Kyoto, Japan

Residence of fourth inventor

Signature of fourth inventor

Date of this assignment

Cornelis Marinus SCHEP

Name of fifth inventor

Execution date of U.S. Patent Application

Eindhoven, The Netherlands

Residence of fifth inventor

Signature of fifth inventor

Date of this assignment

Hermanus Johannes BORG

Name of sixth inventor

Execution date of U.S. Patent Application

Eindhoven, The Netherlands

Residence of sixth inventor

Signature of sixth inventor

Date of this assignment

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NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

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Shoei KOBAYASHI

Name of first or sole inventor Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of first or sole inventor

Signature of first or sole inventor Date of this assignment

Tamotsu YAMAGAMI

Name of second inventor Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of second inventor

Signature of second inventor Date of this assignment

Shin-ichi KADOWAKI

Name of third inventor

Execution date of U.S. Patent Application

Hyogo, Japan

Residence of third inventor

Shin-ichi Kadowaki

January 27, 2005

Signature of third inventor

Date of this assignment

Takashi ISHIDA

Name of fourth inventor

Execution date of U.S. Patent Application

Kyoto, Japan

Residence of fourth inventor

Takashi Ishida

January 27, 2005

Signature of fourth inventor

Date of this assignment

Cornelis Marinus SCHEP

Name of fifth inventor

Execution date of U.S. Patent Application

Eindhoven, The Netherlands

Residence of fifth inventor

Signature of fifth inventor

Date of this assignment

Hermanus Johannes BORG

Name of sixth inventor

Execution date of U.S. Patent Application

Eindhoven, The Netherlands

Residence of sixth inventor

Signature of sixth inventor

Date of this assignment

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Shoei KOBAYASHI

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Kanagawa, Japan

Residence of first or sole inventor

Signature of first or sole inventor

Date of this assignment

Tamotsu YAMAGAMI

Name of second inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of second inventor

Signature of second inventor

Date of this assignment

Shin-ichi KADOWAKI

Name of third inventor

Execution date of U.S. Patent Application

Hyogo, Japan

Residence of third inventor

Signature of third inventor

Date of this assignment

Takashi ISHIDA

Name of fourth inventor

Execution date of U.S. Patent Application

Kyoto, Japan

Residence of fourth inventor

Signature of fourth inventor

Date of this assignment

Cornelis Marinus SCHEP

Name of fifth inventor

Execution date of U.S. Patent Application

Eindhoven, The Netherlands

Residence of fifth inventor

Signature of fifth inventor

11 February 2005

Date of this assignment

Hermanus Johannes BORG

Name of sixth inventor

Execution date of U.S. Patent Application

Eindhoven, The Netherlands

Residence of sixth inventor

Signature of sixth inventor

14 February 2005

Date of this assignment